

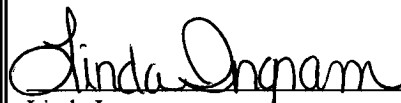
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|                        |   |                        |
|------------------------|---|------------------------|
| In re application of:  | § | Attorney Docket No.    |
| Hsien-Wei Chen, et al. | § | 2003-1410 / 24061.193  |
|                        | § |                        |
| Serial No.: 10/801,475 | § | Customer No. 42717     |
|                        | § |                        |
| Filed: March 16, 2004  | § | Group Art Unit: 2822   |
|                        | § |                        |
| For: SYSTEM FOR HEAT   | § | Examiner: Monica Lewis |
| DISSIPATION IN         | § |                        |
| SEMICONDUCTOR DEVICES  | § | Confirmation No.: 1783 |

Mail Stop Amendment  
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Sir:

I hereby certify that this correspondence (including any listed enclosures) is being electronically filed in the United States Patent and Trademark Office via the EFS-Web system on June 29, 2007.

  
Linda Ingram

**RESPONSE UNDER 37 C.F.R. §1.111**

This Response is submitted in reply to the Office Action mailed on April 5, 2007. (Please see the pages that follow).